



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND
WAFER SCALE INTERPOSER
SUBSTRATE MEMBER FOR USE WITH
FLIP-CHIP CONFIGURED
SEMICONDUCTOR DICE

Confirmation No.: 4215

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-4973.1US
(00-0593.01/US)

Notice of Allowance Mailed:

January 26, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995987189US

Date of Deposit with USPS: April 26, 2006

Person making Deposit: Timothy Palfreyman

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

*OK
to enter
the
6/29/06*

Serial No. 10/782,270

Amendments to the Specification begin on page 3 of this paper;

Amendments to the Claims are set forth in the listing of the claims that begins on page 19 of this paper;

Remarks start at page 24 of this paper.